



## Material Content Data Sheet



<b>Sales Product Name</b>		TDA5220		<b>Issued</b>		28. August 2013		
<b>MA#</b>		MA000226486						
<b>Package</b>		PG-TSSOP-28-1		<b>Weight*</b>		106.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.457	2.30	2.30	22970	22970
leadframe	non noble metal	nickel	7440-02-0	14.398	13.46		134584	
	non noble metal	iron	7439-89-6	19.882	18.59	32.05	185855	320439
wire	noble metal	gold	7440-57-5	0.938	0.88	0.88	8770	8770
encapsulation	organic material	carbon black	1333-86-4	0.196	0.18		1833	
	plastics	epoxy resin	-	8.301	7.76		77597	
	inorganic material	silicondioxide	60676-86-0	56.867	53.15	61.09	531574	611004
leadfinish	non noble metal	tin	7440-31-5	1.539	1.44	1.44	14391	14391
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13233	13233
glue	plastics	acrylic resin	-	0.197	0.18		1839	
	noble metal	silver	7440-22-4	0.787	0.74	0.92	7354	9193
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com